

**QF3075**
*No Clean Liquid Flux*

**Product Description**

QF3075 is a no-clean, halide free RMA flux. It is specially designed to improve effectiveness in lead free wave soldering. QF3075 provides matte solder joints and excellent solderability, with reduction in micro-solderballing and solder bridging at connectors and QFP. The residue left behind is non-tacky, non-corrosive and non-conductive.

**Application**

QF3075 is specially formulated for spraying as well as foaming and dipping process. Recommended onboard preheat temperature is 90 – 110 °C.

**Residue Removal**

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

**Recommended Solvent**

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

**Health and Safety**

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

**Storage**

Under proper storage condition, QF3075 can be stored for up to 6 months. QF3075 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

**Packaging**

Available in 18kg/carboy.

**Specification**

Item	Result
State	Clear and transparent liquid
Colour	Pale yellow
Specific Gravity @ 25°C	0.815 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	7.5 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	38.0 +/- 2 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 <sup>5</sup> Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
<small>JIS Z 3197 8.5.3</small>	> 1 x 10 <sup>11</sup> Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROM0
<small>IPC J-STD-004</small>	
Spread Factor	> 80% (SCS7)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Matte

**DISCLAIMER OF LIABILITY**

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**Singapore Asahi Chemical and Solder Industries Pte Ltd**

47 Pandan Road Singapore 609288

Tel: +65 6262-1616 Fax: +65 6261-6311

 Website: <http://www.asahisolder.com> Email: [enquiry@sinasahi.com.sg](mailto:enquiry@sinasahi.com.sg)